

U_FPGA_IO
FPGA_IO.SchDoc

U_FPGA_MGT
FPGA_MGT.SchDoc

U_FPGA_MISC
FPGA_MISC.SchDoc

U_B2B_Connector
B2B_Connector.SchDoc

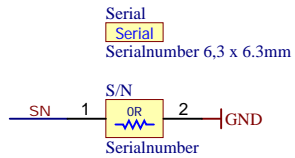
U_POWER
POWER.SchDoc

U_Revision
Revision Changes.SchDoc

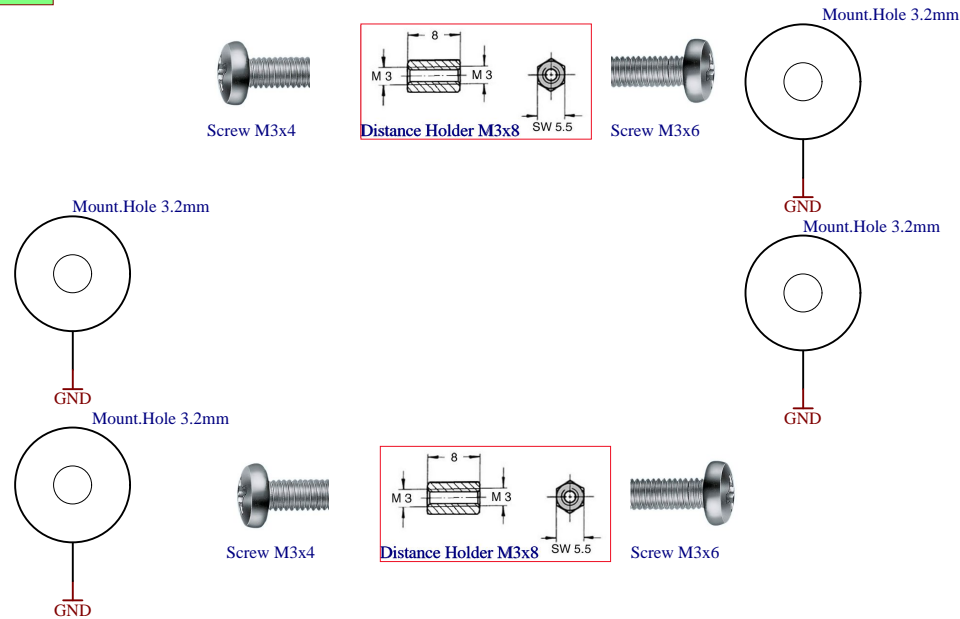
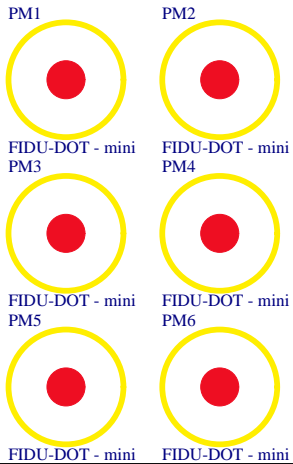
Special notes:

-
-

Top of Board



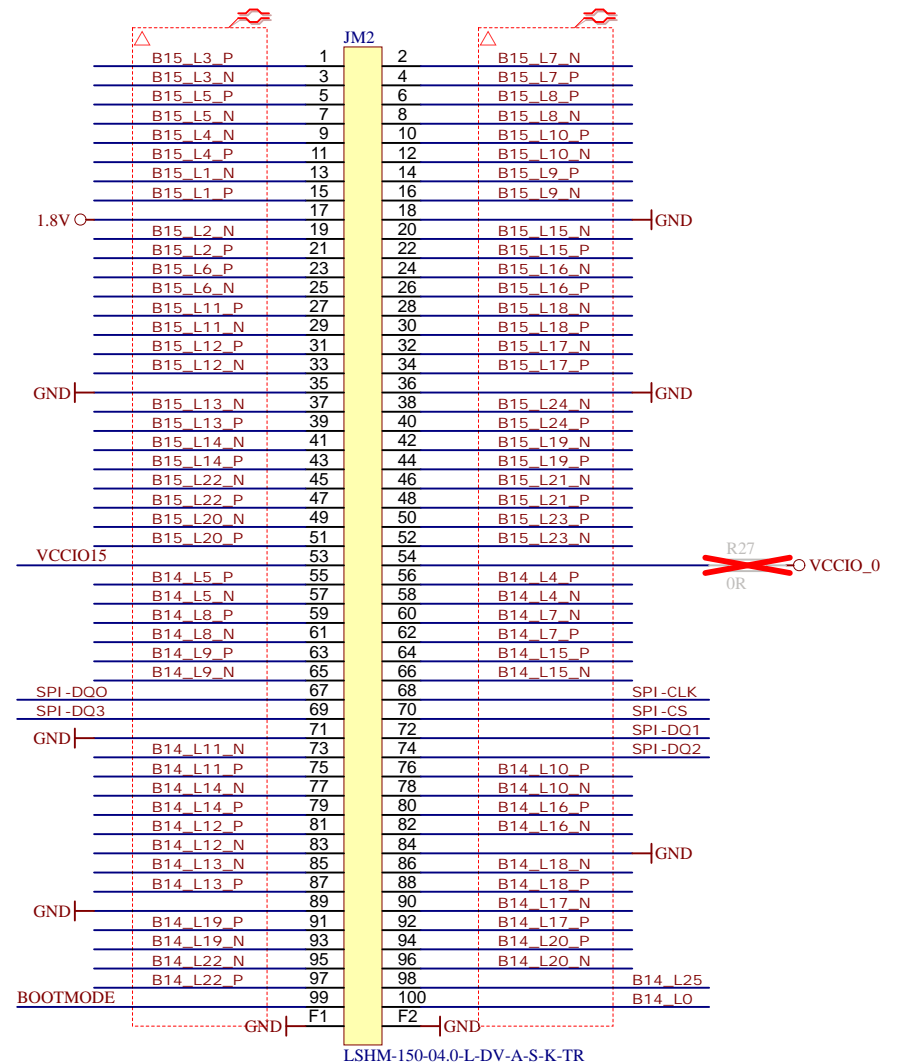
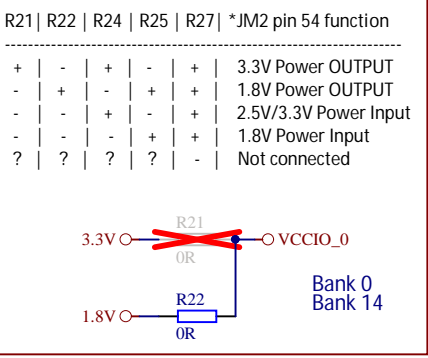
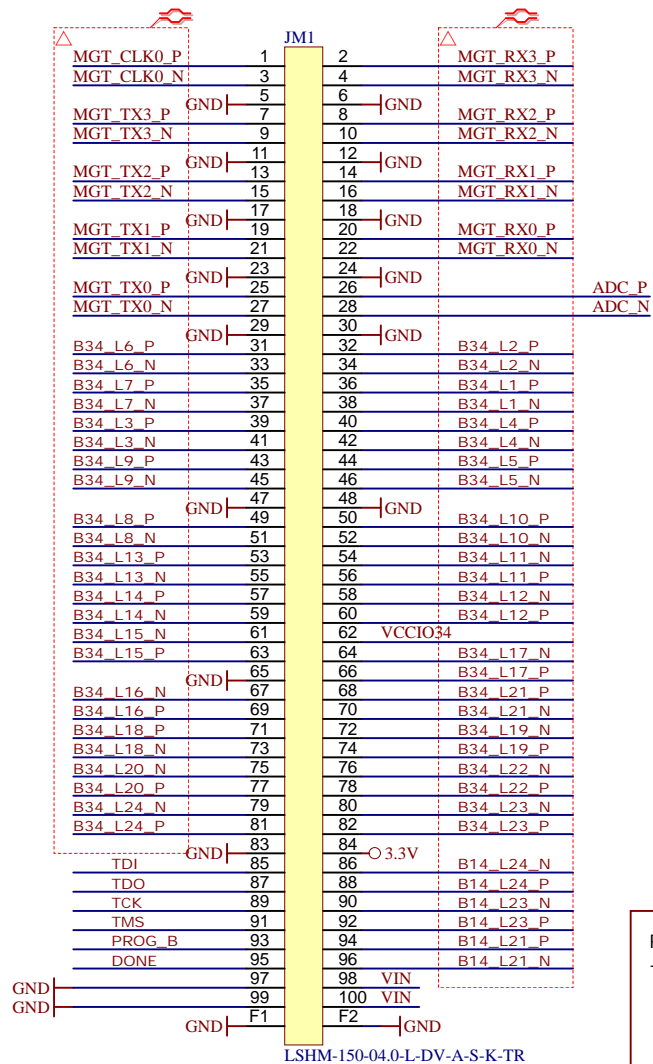
LOGO1
TE Logo PRINT Layer
LOGO PRINT



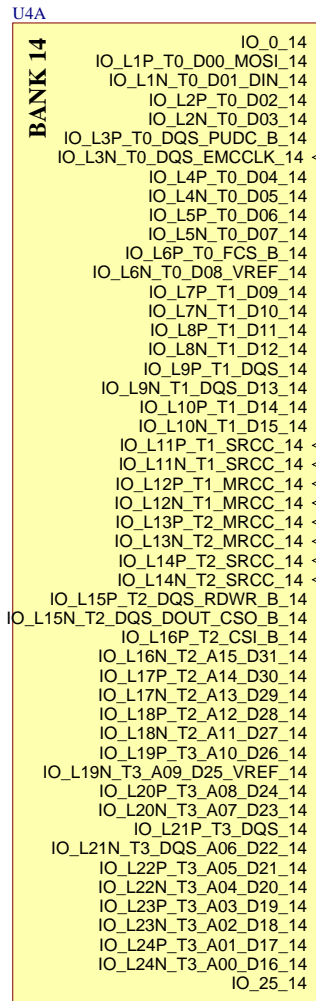
| | |
|------------------|---------|
| Assembly variant | 35-2IC6 |
| Created by | |
| Modified by | |
| Modified at | |
| SVN Revision | 8634 |



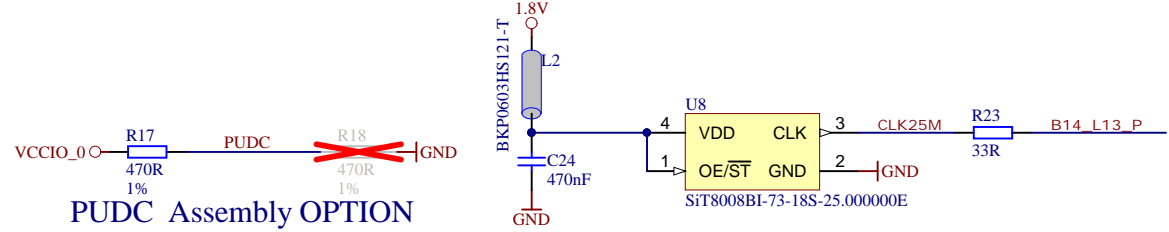
| | | |
|-------------------------|---------------------------------------|------------|
| Title: TE0714 | | |
| A4 | Number: TE0714 35-2IC6 | Rev. 03 |
| Date: 2019-02-14 | Copyright: Trenz Electronic GmbH / TT | Page1 of 7 |
| Filename: TE0714.SchDoc | | |



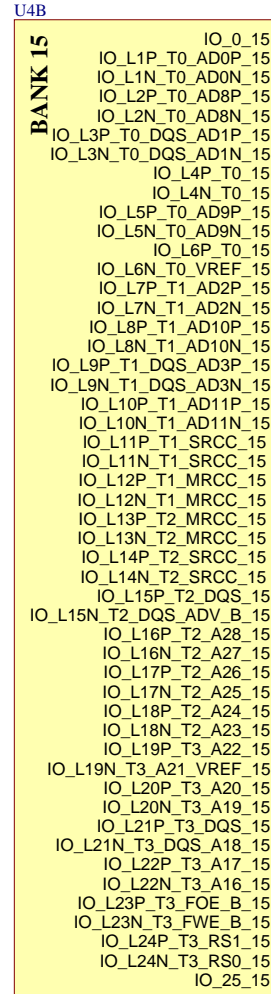
| | | |
|--------------------------------|---------------------------------------|------------|
| Title: TE0714 | | |
| A4 | Number: TE0714 35-2IC6 | Rev. 03 |
| Date: 2019-02-14 | Copyright: Trenz Electronic GmbH / TT | Page2 of 7 |
| Filename: B2B_Connector.SchDoc | | |



XC7A35T-2CSG325I



1

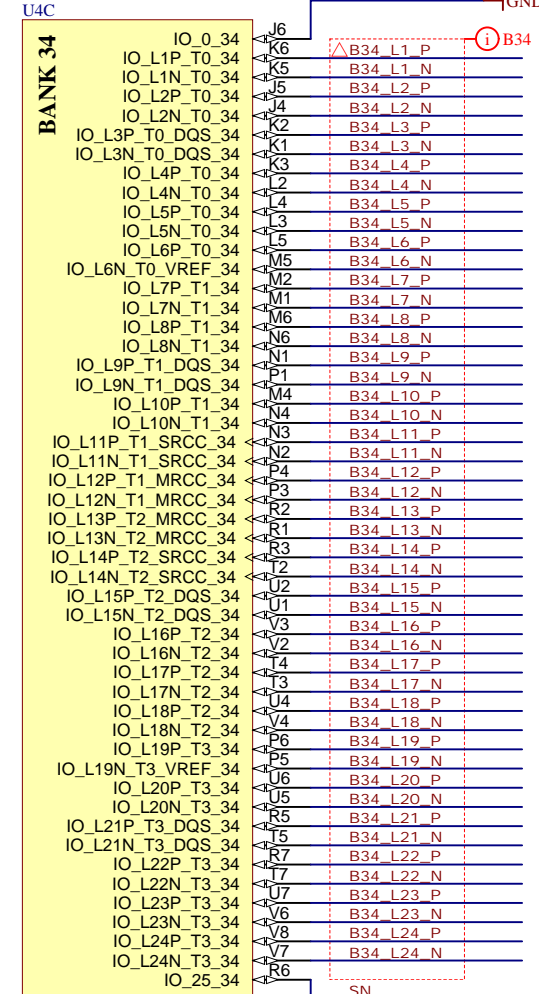


XC7A35T-2CSG325I

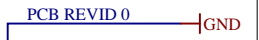


| | | |
|---------------------------------|---------------------------------------|----------------|
| Title: TE0714 | | Rev. 03 |
| A4 | Number: TE0714 35-2IC6 | Page3 of 7 |
| Date: 2019-02-14 | Copyright: Trenz Electronic GmbH / TT | |
| Filename: FPGA_IO.SchDoc | | |

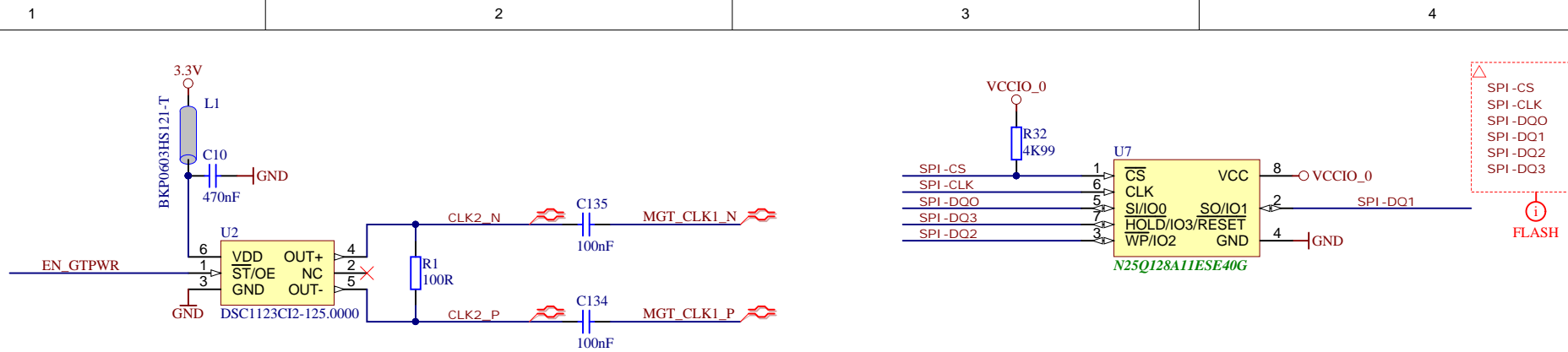
3



XC7A35T-2CSG325I

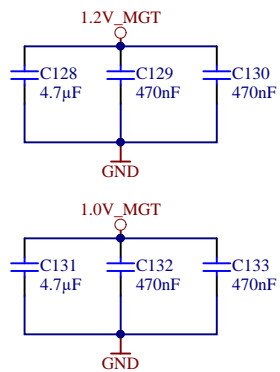
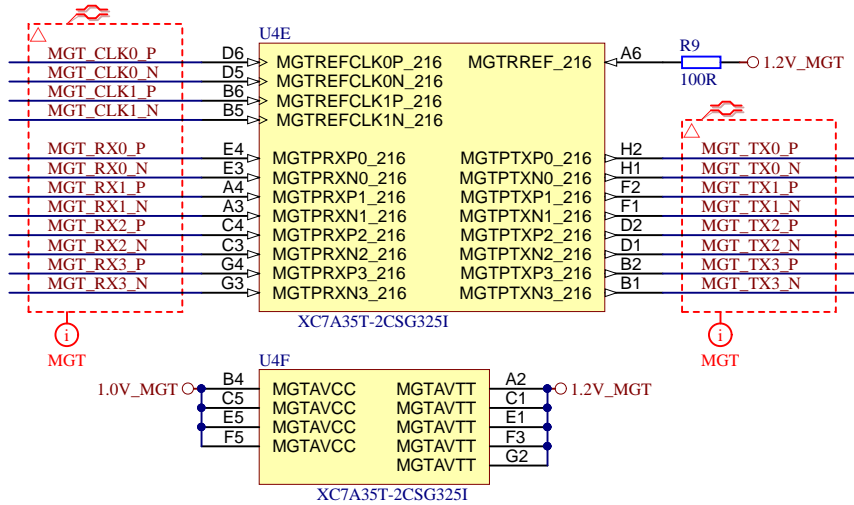



4



△ SPI-CS
 SPI-CLK
 SPI-DQ0
 SPI-DQ1
 SPI-DQ2
 SPI-DQ3

FLASH



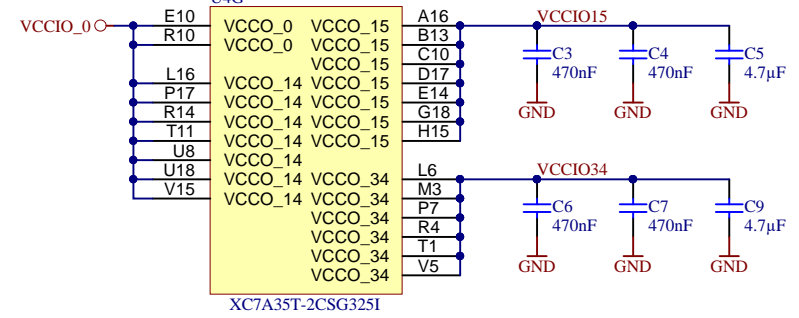
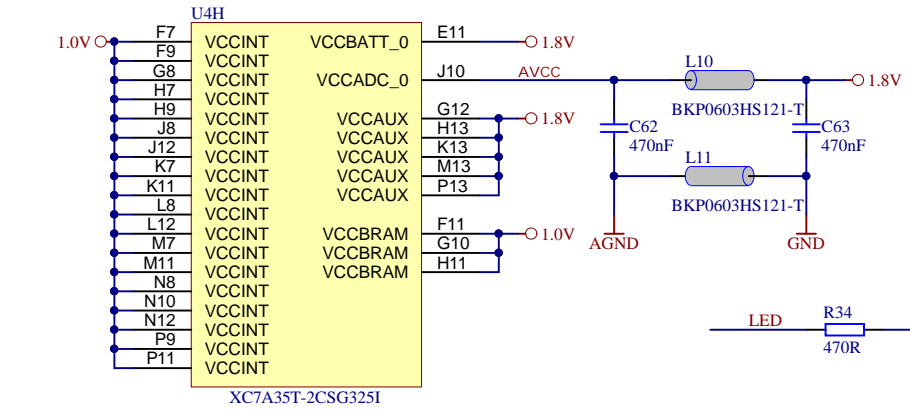
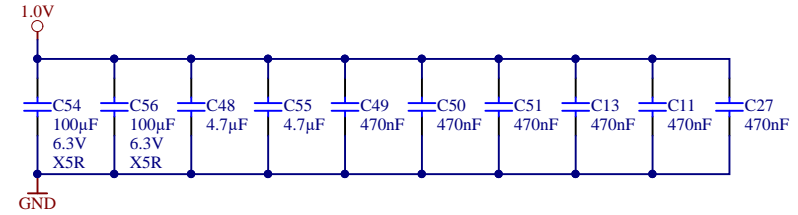
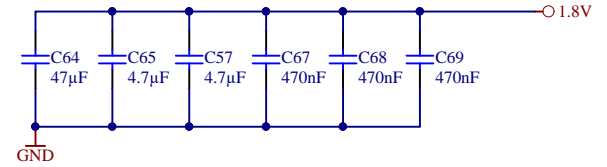
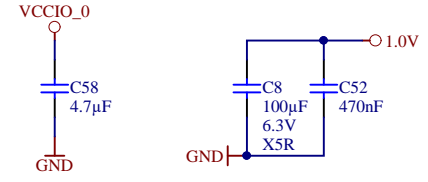
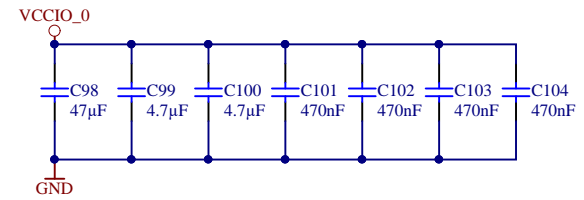
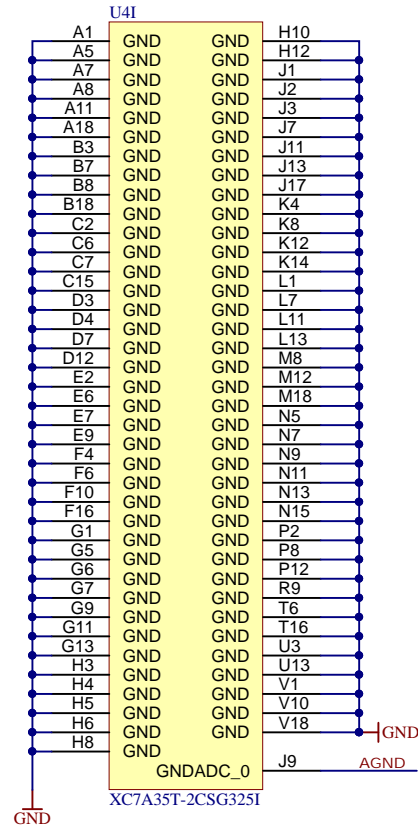
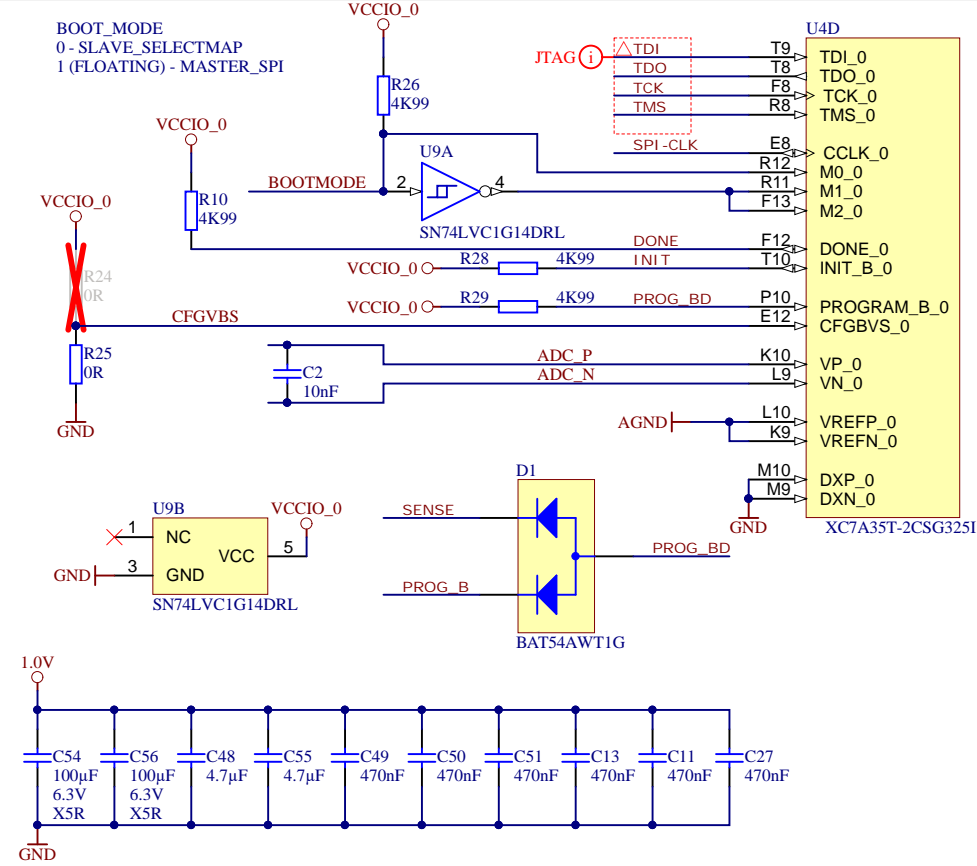
| | | | | |
|---|--|---------------------------------------|---------------|---------------------------|
|  | | | Title: TE0714 | |
| | | | A4 | Number: TE0714 35-2IC6 |
| Date: 2019-02-14 | | Copyright: Trenz Electronic GmbH / TT | | Page 4 of 7 |
| Filename: FPGA_MGT.SchDoc | | | | |

A

B

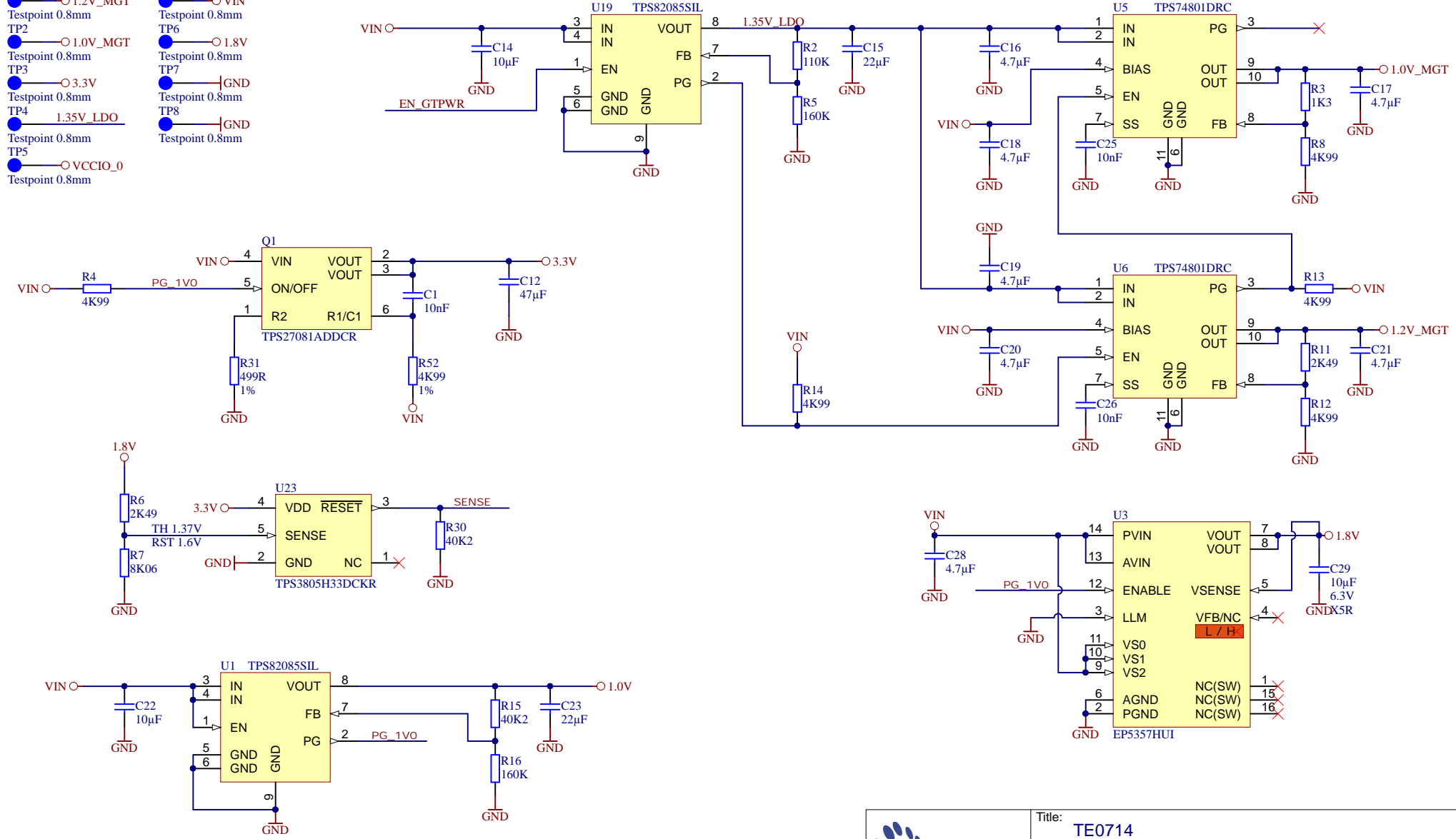
C

D



| | | |
|----------------------------|---------------------------------------|------------|
| Title: TE0714 | | |
| A4 | Number: TE0714 35-2IC6 | Rev. 03 |
| Date: 2019-02-14 | Copyright: Trenz Electronic GmbH / TT | Page5 of 7 |
| Filename: FPGA_MISC.SchDoc | | |

- TP1 ● ○ 1.2V_MGT
Testpoint 0.8mm
- TP2 ● ○ 1.0V_MGT
Testpoint 0.8mm
- TP3 ● ○ 3.3V
Testpoint 0.8mm
- TP4 ● ○ 1.35V_LDO
Testpoint 0.8mm
- TP5 ● ○ VCCIO_0
Testpoint 0.8mm
- TP9 ● ○ VIN
Testpoint 0.8mm
- TP6 ● ○ 1.8V
Testpoint 0.8mm
- TP7 ● ○ GND
Testpoint 0.8mm
- TP8 ● ○ GND
Testpoint 0.8mm



| | | |
|-------------------------------|---|---------------------------|
| Title: TE0714 | | |
| A4 | Number: TE0714 35-2IC6 | Rev. 03 |
| Date: 2019-02-14 | Copyright: Trenz Electronic GmbH | Page 6 of 7 |
| Filename: POWER.SchDoc | | |

1

2

3

4

Changes REV 02:

- 1. Added 0 ohm strap option to supply VCCIO0 on B2B connector
- 2. Added PCB Revision sense support. PCB Revision readout possible from HDL Design
- 3. Updated FPGA pin PROG_B connection. TPS3805H33 push-pull output RESET_N not affected on baseboard circuit, connected to PROG_B.
- 4. C8, C54, C56 updated to 100uF for variant 50-2I
- 5. Added testpoints

Changes REV 02A (12.2018):

- 1. New FLASH memory U7 S25FL127SABMFV10

Changes REV 03:

- 1) Changed obsolete component U3 (LXDC2HL18A-052 -> EP5357HUI)
- 2) DXP/DXN connected to GND (recommendation UG475, p31)
- 3) Added serial number to silk
- 4) Changed obsolete component Q1 (TPS27082LDDCR ->TPS27081ADDCR)
- 5) Full update LIB
- 6) Optimized testpoints placement

A

A

B


B

C

C

D

D

| | | | |
|---|--|--|---------------------------|
|  | Title: TE0714 | | |
| | A4 | Number: TE0714 35-2IC6 | Rev. 03 |
| | Date: 2019-02-14 | Copyright: Trenz Electronic GmbH / TT | Page 7 of 7 |
| | Filename: Revision Changes.SchDoc | | |

1

2

3

4